



Title of Change:	Qualification of NCP706 at AMKOR Philippines.	
Proposed first ship date:	13 August 2015	
Contact information:	Contact your local ON Semiconductor Sales Office or <Jaroslav.Supina@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Tomas.Vajter@onsemi.com>.	
Type of notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.</p>	
Change Part Identification:	Assembly site information is included in the device traceability coding	
Change category(s): <input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change	<input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected: <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s):	<u>Site 1</u> Amkor Technology Philippines P3	<u>Site 2</u>
Description and Purpose: The NCP706MX21TAG and the NCP706MC22TAG has been qualified for assembly in the XDFN8 1.2*1.6*.4 package and will be assembled in Amkor Philippines as a supplemental assembly site. This is a capacity expansion. Note: Other output voltage versions of this same device has previously been qualified at Amkor from the original part introduction and are not listed on this FPCN.		

**Reliability Data Summary:**

Generic Qualification data based on the NCP154 in the same package and technology

#	Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ ss)	(rej/ ss)	(rej/ ss)
					Read Point	A	B	C
	Prep	Sample preparation and initial part testing	various	---	Initial Electrical	done	done	done
A1	PC (MSL1)	MSL1 Preconditioning	3 IR @ 260 deg C	c = 0, 25°C		done	done	done
A2	HAST- PC	Precon. HAST	131°C/85%RH/18.8 psig	c = 0, 25°C & 125°C	96hrs.	0/80	0/80	0/79
A3	UHST- PC	Precon. Unbias - HAST	131°C/85%RH/18.8 psig	c = 0, 25°C	96hrs.	0/80	0/80	0/80
A4	TC- PC	Precond. Temp Cycle	-65/+150 C	c = 0, 25°C, 125°C	500 cyc 1000cyc	0/80 0/80	0/80 0/80	0/80 0/80
A6	HTSL	High Storage Life	150°C for 1008 hours	c = 0, 25°C, 125°C	504 Hrs 1008hrs.	0/80 0/80		
B1	HTOL	High Temp Op Life	TA = 125°C for 504 hours	c = 0, 25°C & 125°C	504 Hrs	0/80		
	SAT	Scanning Acoustic Tomography	Compare for Delamination before and after PC	Compare to existing data	Results	Without delamination	Without delamination	Without delamination
C2	BPS	Bond Pull Strength	Cond C.	Min Cpk 1.33	post TC500	Pass		
	CDPA	Customer DPA	Customer Destructive Physical Analysis		TC500	pass	pass	pass
E5	ED	Electrical Distribution	Critical Parameters	-40°C, 25°C, 125°C	Results	Cpk>1.67		

Electrical Characteristic Summary:

Testing of these parts will continue to be performed at the existing ON Semiconductor factory. Electrical characteristics are not impacted.

List of Affected Standard Parts:

NCP706MX21TAG

NCP706MX22TAG